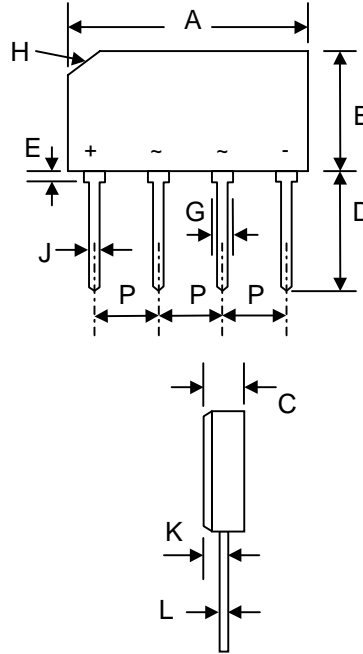


### Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability
- Ideal for Printed Circuit Boards



GBL		
Dim	Min	Max
A	19.6	20.6
B	10.7	11.2
C	3.8	4.7
D	15.7	17.3
E	1.65	2.4
G	1.65	2.0
H	3.17 x 45°	
J	0.90	1.14
K	1.14	1.52
L	0.38	0.51
P	4.8	5.3
All Dimensions in mm		

### Mechanical Data

- Case: Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Body
- Weight: 2.0 grams (approx.)
- Mounting Position: Any
- Marking: Type Number

### Maximum Ratings and Electrical Characteristics @ $T_A=25^\circ\text{C}$ unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

Characteristic	Symbol	GBL 005	GBL 01	GBL 02	GBL 04	GBL 06	GBL 08	GBL 10	Unit
Peak Repetitive Reverse Voltage	$V_{RRM}$								
Working Peak Reverse Voltage	$V_{RWM}$	50	100	200	400	600	800	1000	V
DC Blocking Voltage	$V_R$								
RMS Reverse Voltage	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Average Rectified Output Current @ $T_C = 50^\circ\text{C}$	$I_o$	4.0							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	150							A
Forward Voltage (per bridge) @ $I_F = 4.0\text{A}$	$V_{FM}$	1.0							V
Peak Reverse Current @ $T_A = 25^\circ\text{C}$	$I_R$	10							$\mu\text{A}$
At Rated DC Blocking Voltage @ $T_C = 150^\circ\text{C}$		1.0							$\text{mA}$
Typical Thermal Resistance (per leg) (Note 1)	$R_{\theta JA}$	22							$^\circ\text{C/W}$
Typical Thermal Resistance (per leg) (Note 2)	$R_{\theta JC}$	3.5							$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_j, T_{STG}$	-55 to +150							$^\circ\text{C}$

Note: 1. Thermal resistance junction to ambient, mounted on 7.5 x 7.5 x 0.3cm thick AL plate.  
2. Thermal resistance junction to case, mounted on PCB at 9.5mm lead length.

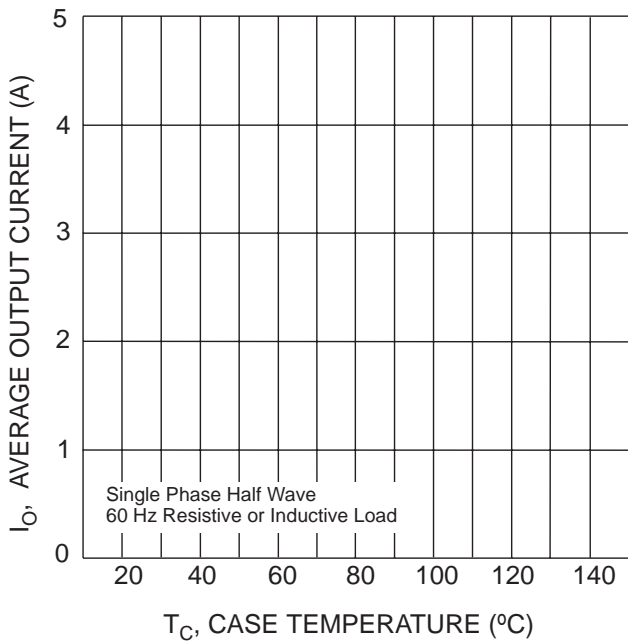


Fig. 1 Forward Current Derating Curve

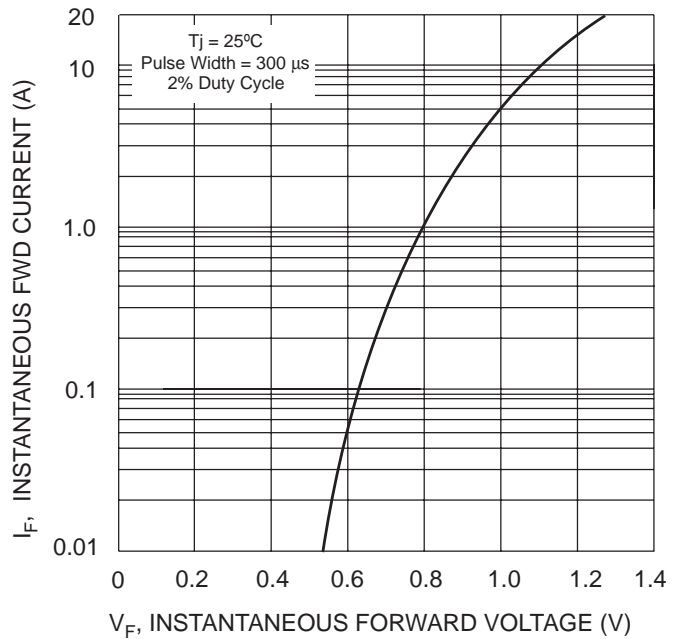


Fig. 2 Typical Forward Characteristics, per element

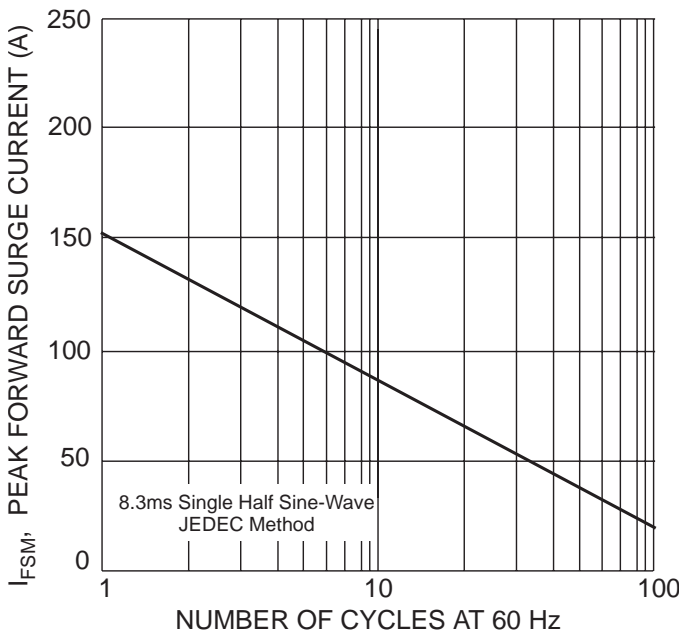


Fig. 3 Max Non-Repetitive Peak Fwd Surge Current

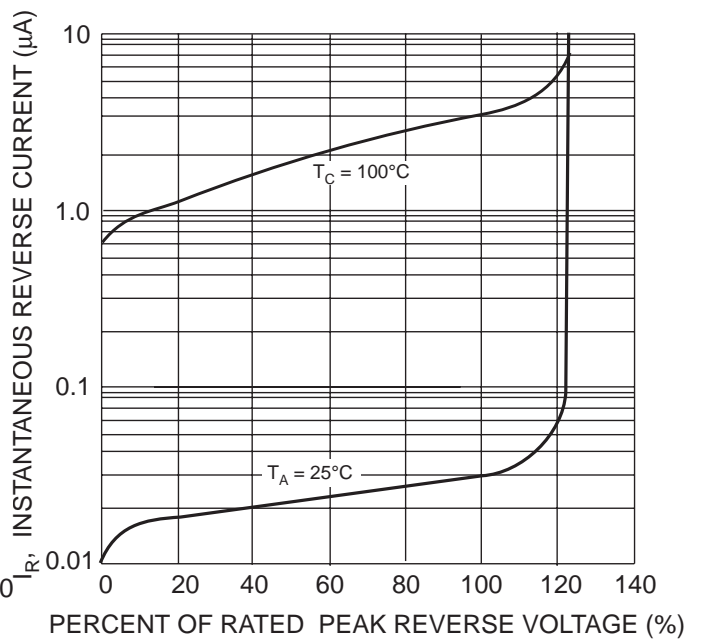


Fig. 4 Typical Reverse Characteristics, per element

## ORDERING INFORMATION

Product No.	Package Type	Shipping Quantity
GBL005	SIL Bridge	500 Units/Box
GBL01	SIL Bridge	500 Units/Box
GBL02	SIL Bridge	500 Units/Box
GBL04	SIL Bridge	500 Units/Box
GBL06	SIL Bridge	500 Units/Box
GBL08	SIL Bridge	500 Units/Box
GBL10	SIL Bridge	500 Units/Box

Shipping quantity given is for minimum packing quantity only. For minimum order quantity, please consult the Sales Department.

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